



# P-Channel 12 V (D-S) MOSFET

MOSFET PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$ Max.	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)			
	0.028 at V <sub>GS</sub> = - 4.5 V	- 6 <sup>e</sup>				
- 12	0.032 at V <sub>GS</sub> = - 3.7 V	- 6 <sup>e</sup>				
	0.040 at V <sub>GS</sub> = - 2.5 V	- 6 <sup>e</sup>	9 nC			
	0.063 at V <sub>GS</sub> = - 1.8 V	- 4.5				
	0.150 at V <sub>GS</sub> = - 1.5 V	- 3.6				

#### **FEATURES**

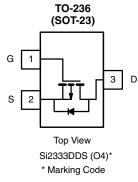
- TrenchFET® Power MOSFET
- 100 % R<sub>g</sub> Tested
- Material categorization: For definitions of compliance please see www.vishav.com/doc?99912



HALOGEN FREE

#### **APPLICATIONS**

- Smart Phones and Tablet PCs
  - Load Switch
  - Battery Switch



Ordering Information: Si2333DDS-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS $(T_A$	= 25 °C, unless ot	herwise noted)		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	- 12	V
Gate-Source Voltage	$V_{GS}$	± 8	7 °	
	T <sub>C</sub> = 25 °C		- 6 <sup>e</sup>	
Continuous Drain Current (T <sub>.1</sub> = 150 °C)	T <sub>C</sub> = 70 °C	L_	- 5.2	
Continuous Diain Guiterit (1) = 130 G)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	- 5 <sup>b, c</sup>	
	T <sub>A</sub> = 70 °C		- 4 <sup>b, c</sup>	Α
Pulsed Drain Current (t = 300 μs)	I <sub>DM</sub>	- 20	7	
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	I <sub>S</sub>	- 1.4	
Continuous Source-Diain Diode Current	T <sub>A</sub> = 25 °C	'S	- 0.63 <sup>b, c</sup>	
	T <sub>C</sub> = 25 °C		1.7	
Maximum Power Dissipation	T <sub>C</sub> = 70 °C	$P_{D}$	1.1	w
Maximum i Ower Dissipation	T <sub>A</sub> = 25 °C	'D	1.20 <sup>b, c</sup>	
	T <sub>A</sub> = 70 °C		0.6 <sup>b, c</sup>	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>sta</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>b, d</sup>	≤ 5 s	R <sub>thJA</sub>	100	130	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	60	75	O/ V V		

- a. Based on  $T_C$  = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 175 °C/W.
- e. Package limited.



MOSFET SPECIFICATIONS (T <sub>J</sub> = 25 °C, unless otherwise noted)							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	1				T	1	
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{DS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	- 12			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = - 250 μΑ		- 8		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			2.4			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = -250 \mu A$	- 0.4		- 1	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	lpee	V <sub>DS</sub> = - 12 V, V <sub>GS</sub> = 0 V			- 1	μΑ	
Zero date voltage Brain ourient	IDSS	$V_{DS} = -12 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$	-		- 10		
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$V_{DS} \le$ - 5 V, $V_{GS}$ = - 4.5 V	- 20			Α	
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 5 A		0.023	0.028		
		V <sub>GS</sub> = - 3.7 V, I <sub>D</sub> = - 4.6 A		0.026	0.032		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 4.3 A		0.033	0.040	Ω	
	,	V <sub>GS</sub> = - 1.8 V, I <sub>D</sub> = - 1 A		0.048	0.063		
		V <sub>GS</sub> = - 1.5 V, I <sub>D</sub> = - 0.5 A		0.075	0.150		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 5 V, I <sub>D</sub> = - 5 A		18		S	
Dynamic <sup>b</sup>					L	L	
Input Capacitance	C <sub>iss</sub>			1275			
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -6 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		255		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			236			
Total Oats Observe		V <sub>DS</sub> = -6 V, V <sub>GS</sub> = -8 V, I <sub>D</sub> = -5 A		23	35		
Total Gate Charge	$Q_g$			14	21		
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -6 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -5 \text{ A}$		2.3		nC	
Gate-Drain Charge	$Q_{gd}$			3.6			
Gate Resistance	Rg	f = 1 MHz	1.9	9.5	19	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			26	40		
Rise Time	t <sub>r</sub>	$V_{DD}$ = - 6 V, $R_{I}$ = 6 $\Omega$		24	40		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D = -4 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_G = 1 \Omega$		45	70	ns	
Fall Time	t <sub>f</sub>			20	35	1	
<b>Drain-Source Body Diode Characterist</b>	cs					I	
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 1.4		
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				- 20	A	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = - 4 A		- 0.8	- 1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			24	48	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			8	16	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = -4 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		9		<del>                                     </del>	
Reverse Recovery Rise Time		t <sub>b</sub>		15		ns	

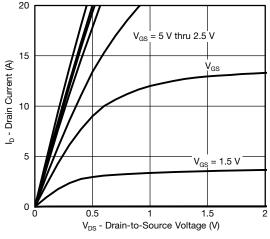
#### Notes:

- a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.

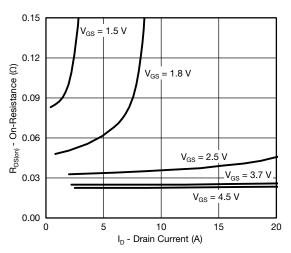
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



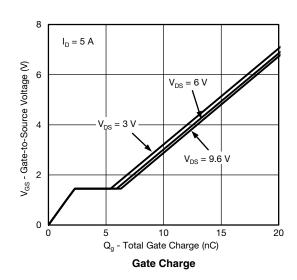
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

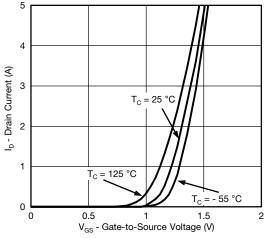




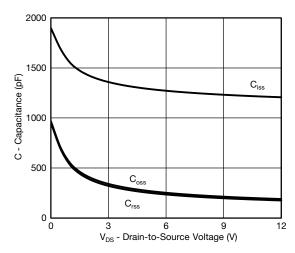


On-Resistance vs. Drain Current and Gate Voltage

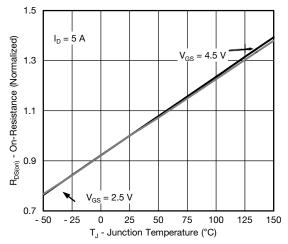




Transfer Characteristics

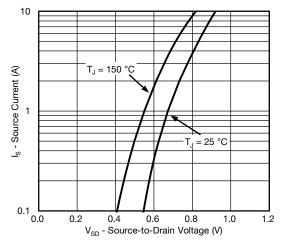


Capacitance

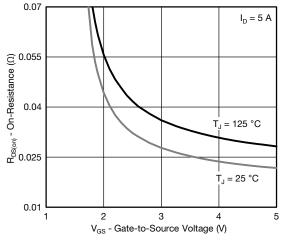


On-Resistance vs. Junction Temperature

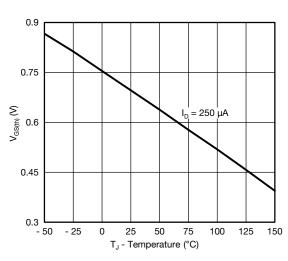
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



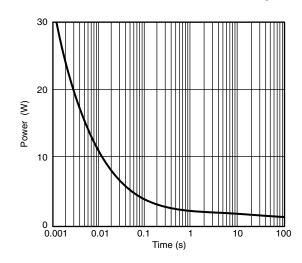
Source-Drain Diode Forward Voltage



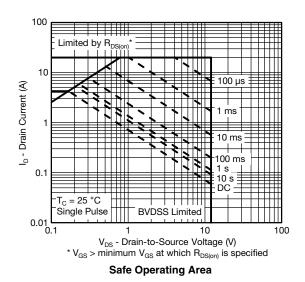
On-Resistance vs. Gate-to-Source Voltage



**Threshold Voltage** 

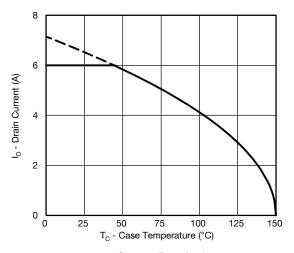


Single Pulse Power

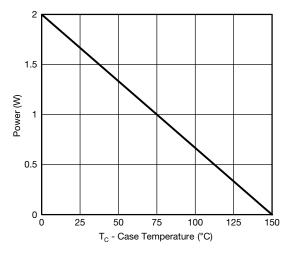




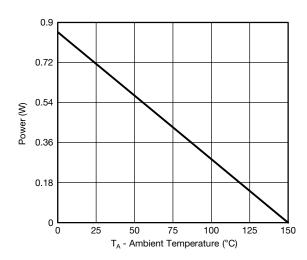
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



#### **Current Derating\***



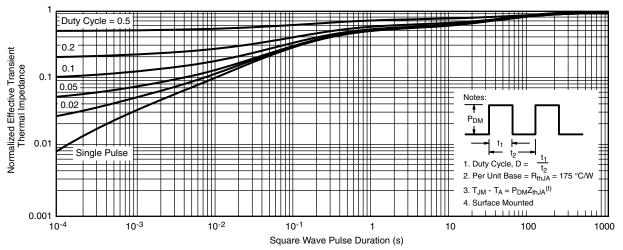




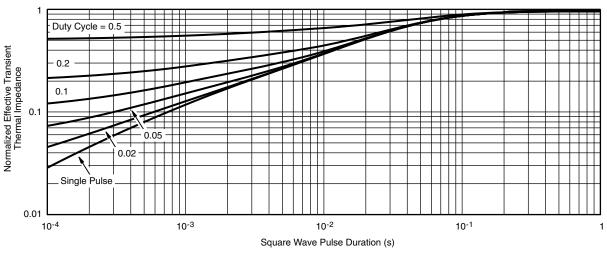
Power, Junction-to-Ambient

<sup>\*</sup> The power dissipation PD is based on TJ(max.) = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



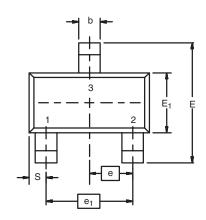
Normalized Thermal Transient Impedance, Junction-to-Ambient

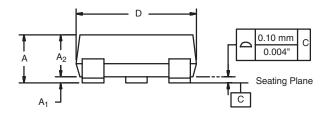


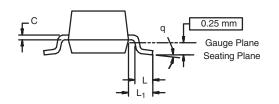
Normalized Thermal Transient Impedance, Junction-to-Foot

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## SOT-23 (TO-236): 3-LEAD







Dim	MILLI	METERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A <sub>1</sub>	0.01	0.10	0.0004	0.004	
A <sub>2</sub>	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E <sub>1</sub>	1.20	1.40	0.047	0.055	
е	0.9	5 BSC	0.037	4 Ref	
e <sub>1</sub>	1.9	0 BSC	0.074	8 Ref	
L	0.40	0.60	0.016	0.024	
L <sub>1</sub>	0.6	64 Ref	f 0.025 Ref		
S	0.5	50 Ref 0.020 R		) Ref	
q	3°	8°	3°	8°	
FCN: S-03946-Rev K 09-	lul-01	•			

ECN: S-03946-Rev. K, 09-Jul-01

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## **RECOMMENDED MINIMUM PADS FOR SOT-23**



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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